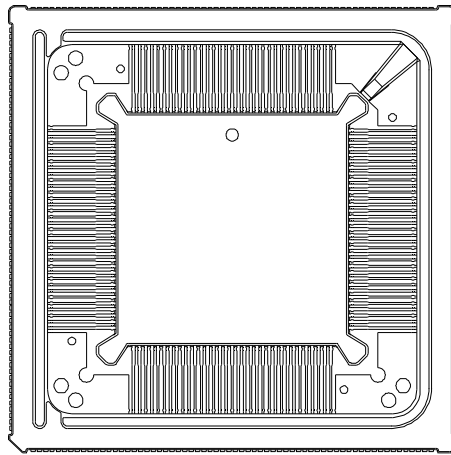
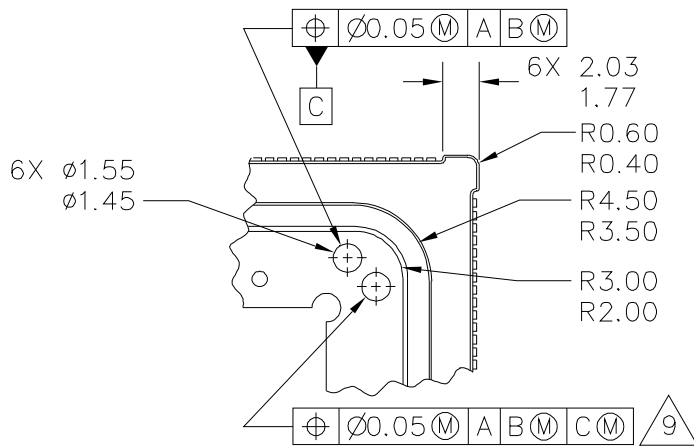


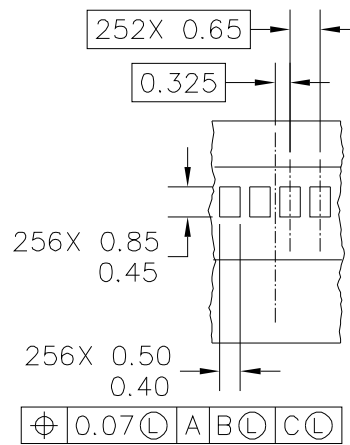
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TITLE: 132 LD PQFP, 256 LD "AB" MOLDED CARRIER RING WITH CORNER TIES & GATE REMOVED	DOCUMENT NO: 98ASS23451W	REV: E
	STANDARD: NON-JEDEC	
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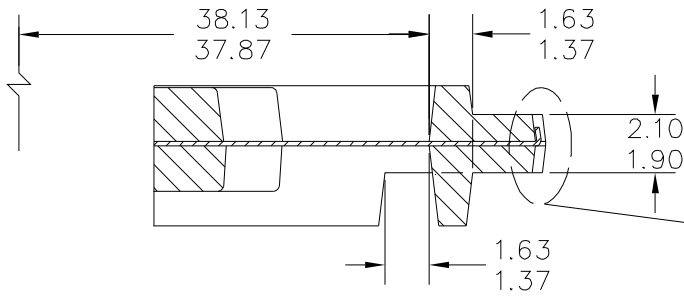
BOTTOM VIEW OF UNIT
IN MOLDED CARRIER RING



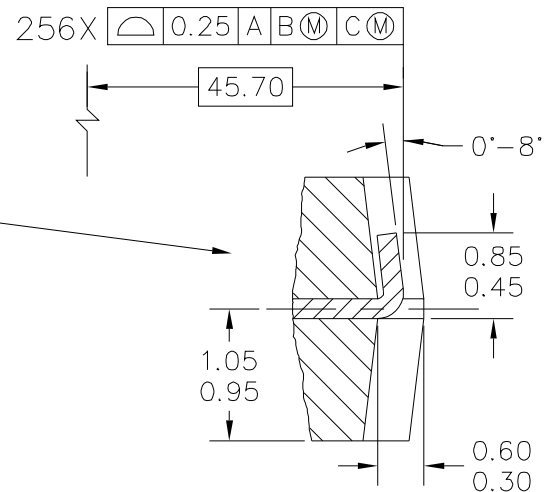
VIEW AR



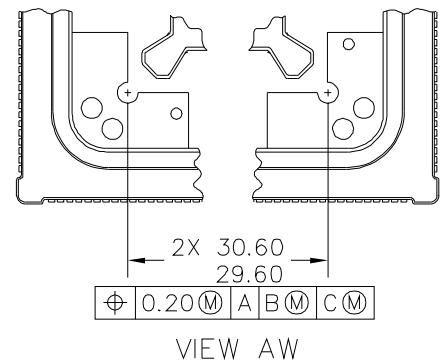
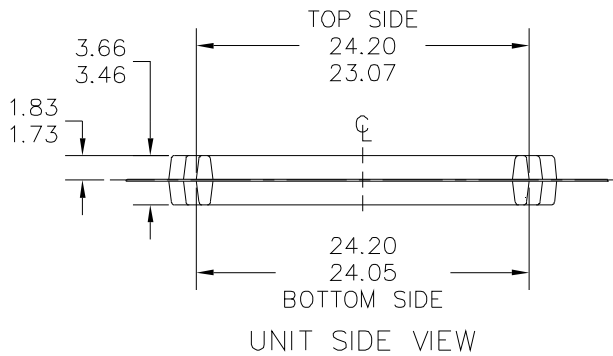
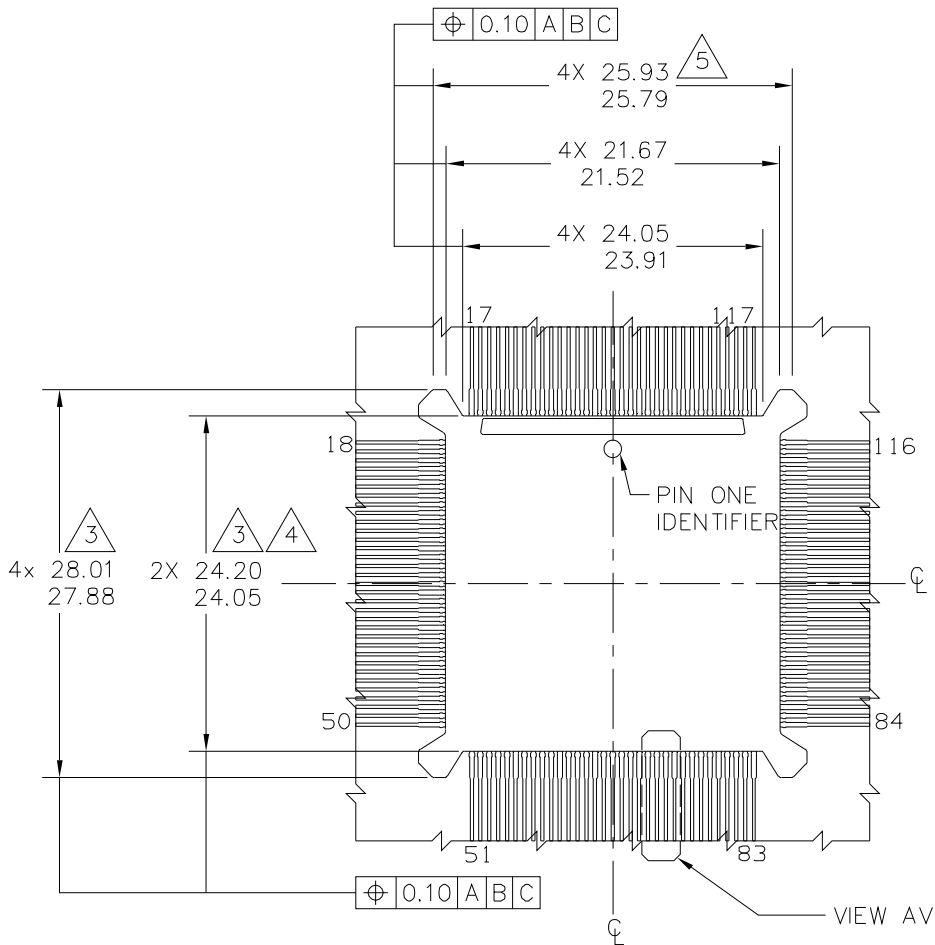
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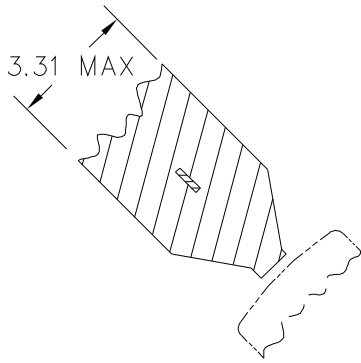
SECTION AK-AK



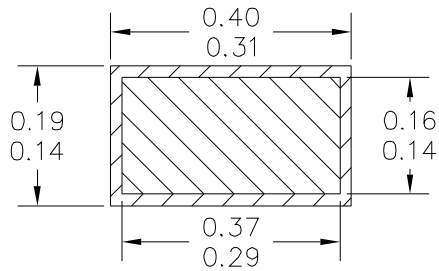
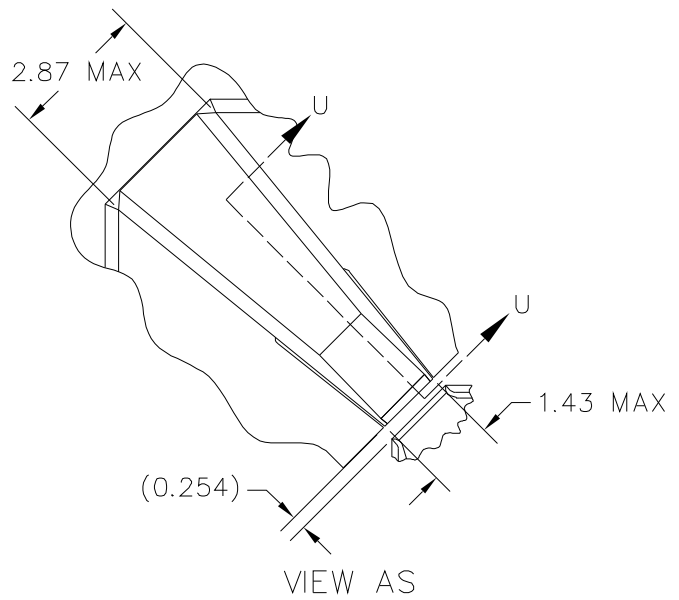
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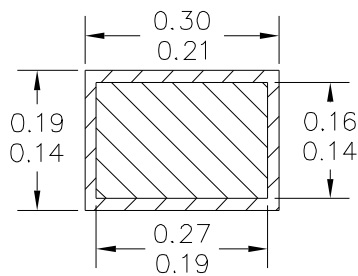
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	STANDARD: NON-JEDEC	
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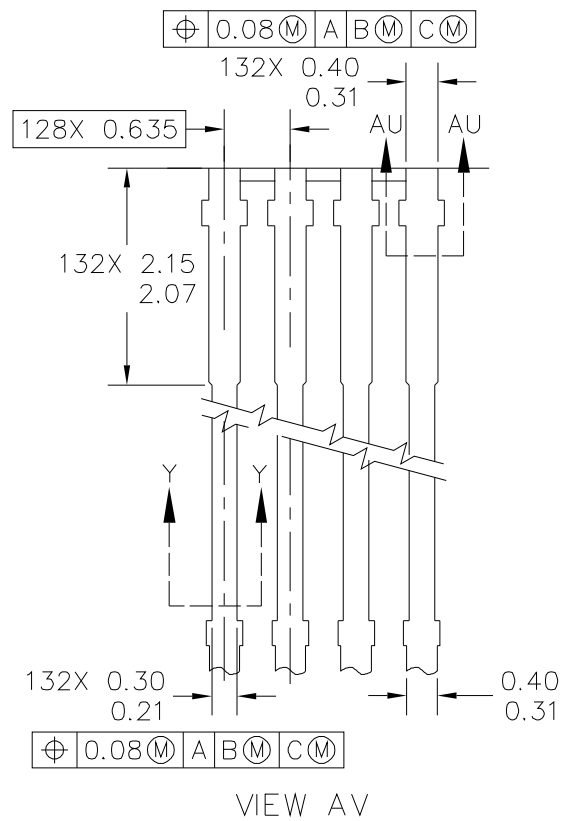
SECTION U-U



SECTION AU-AU



SECTION Y-Y



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	STANDARD: NON-JEDEC	
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NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.20mm PER SIDE.
4. ALLOWABLE MOLD PROTRUSION IS 0.18mm PER SIDE.
5. DIMENSIONS INCLUDE MOLD MISMATCH, AND ARE MEASURED AT THE PARTING LINE.
6. UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE SYMMETRICAL ABOUT CENTERLINES.
7. B AND C DATUM HOLES ARE TO BE USED FOR TRIM. FORM AND EXCISE OF THE MOLDED PACKAGE ONLY.
8. HOLES Q1 AND Q2 ARE TO BE USED FOR ELECTRICAL TESTING ONLY.
9. NON-DATUM HOLES ONLY.
10. APPLIES TO RING AND PACKAGE FEATURES.
11. SOLDER PLATING THICKNESS IS 7.6-15.2 MICRONS WITH TARGET OF 11.43 MICRONS. PLATING COMPOSITION IS 80/20 TIN LEAD WITH ±10 VARIATION. MEASUREMENTS MADE WITH X-RAY FLUORESCENCE (XRF).

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